

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4686979

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SIDDHARTH CHAKRAVARTY	11/02/2017
PRADEEP YELEHANKA	11/03/2017
SHARATH POIKAYIL POIKAYIL SATHEESH	11/08/2017
CHUN HOE YIK	11/03/2017
RAKESH KUMAR	11/03/2017
NATARAJAN RAJASEKARAN	11/03/2017
RECEIVING PARTY DATA	
Name:	GLOBALFOUNDRIES SINGAPORE PTE. LTD.
Street Address:	60 WOODLANDS INDUSTRIAL PARK D STREET 2
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	738406
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15810163
CORRESPONDENCE DATA	
Fax Number:	(656)846-2005
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	6568549880
Email:	oa.notification@horizonip.com.sg
Correspondent Name:	HORIZON IP PTE. LTD.
Address Line 1:	7500A BEACH ROAD, #04-306/308
Address Line 2:	THE PLAZA
Address Line 4:	SINGAPORE, SINGAPORE 199591
ATTORNEY DOCKET NUMBER:	GFSP2016NAT13US0
NAME OF SUBMITTER:	DEXTER CHIN
SIGNATURE:	/dexter chin/
DATE SIGNED:	11/13/2017
This document serves as an Oath/Declaration (37 CFR 1.63).	

PATENT

Total Attachments: 6

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source=GFSP2016NAT13US0-Declaration#page2.tif

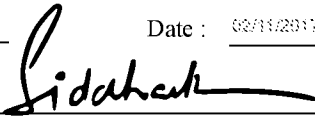
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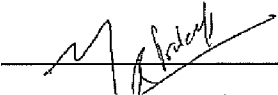
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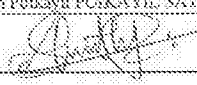
COMBINED DECLARATION and ASSIGNMENT (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)

Title of Invention	WAFER LEVEL PACKAGING FOR MEMS DEVICE
<p style="text-align: center;">DECLARATION</p> <p>As the below named inventor, I hereby declare that:</p> <p>This declaration is directed to: <input checked="" type="checkbox"/> The attached application, or <input type="checkbox"/> United States application or PCT international application number _____ filed on _____</p> <p>The above-identified application was made or authorized to be made by me.</p> <p>I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.</p> <p>I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.</p> <p>I have reviewed and understand the contents of the application and am aware of the duty to disclose to the US Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR § 1.56.</p> <p style="text-align: center;">ASSIGNMENT</p> <p>For good and valuable consideration, the receipt, sufficiency and adequacy of which are hereby acknowledged, I hereby sell, assign, transfer, to GLOBALFOUNDRIES Singapore Pte. Ltd. having a business address of 60 Woodlands Industrial Park D Street 2, Singapore 738406 its successors and assigns, absolutely and forever, my entire right, title and interest in and to the invention listed above, together with the Application, any and all Patents that may issue in the United States and/or any foreign countries, and any reissues, re-examinations, renewals, continuations, continuation-in-parts, divisionals or extensions thereof that may be issued or granted, and all right, title and interest to the inventions contained in said Patents and Applications, for the United States and all foreign countries, and all the rights and privileges relating thereto including but not limited to the priority rights arising from said Applications, the right to recover and take all such proceedings as may be necessary for the recovery of damages or otherwise in respect of past, present and future infringement, and the right to apply for, take and maintain patents on said inventions.</p> <p>If any portion of this Combined Declaration or Assignment is held unenforceable, then remaining portions hereof shall nevertheless remain in full force and effect.</p>	
<p>LEGAL NAME OF INVENTOR</p> <p>Inventor: <u>Siddharth CHAKRAVARTY</u> Date : <u>02/11/2017</u></p> <p>Signature: <u></u></p>	
<p>Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.</p>	

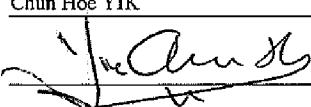
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<p>LEGAL NAME OF INVENTOR</p> <p>Inventor: <u>Pradeep YELEHANKA</u> Date: <u>3 - Nov - 2017</u></p> <p>Signature: <u></u></p> <p>Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.</p>	

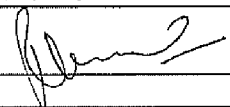
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<p>LEGAL NAME OF INVENTOR</p> <p>Inventor: <u>Sharan Polkayil POLKAYIL SATHIEESH</u> Date: <u>8 Nov 2017</u></p> <p>Signature: <u></u></p>	
<p><small>Note: An application data sheet (PDS/5B/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.</small></p>	

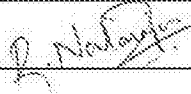
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<p>LEGAL NAME OF INVENTOR</p> <p>Inventor: <u>Chun Hoe YIK</u> Date: <u>3 Nov 2017</u></p> <p>Signature: </p>	
<p>Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.</p>	

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<p>LEGAL NAME OF INVENTOR</p> <p>Inventor: <u>Rakesh KUMAR</u> Date: <u>3/11/17</u></p> <p>Signature: <u></u></p> <p>Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.</p>	

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<p>LEGAL NAME OF INVENTOR</p> <p>Inventor: <u>Natarajan RAJASEKARAN</u> Date: <u>3 - NOV - 2017</u></p> <p>Signature: <u></u></p> <p><small>Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.</small></p>	